Product Change Notification: MFOL-09UGKQ160

Date:

12-Jun-2025

Product Category:

8-Bit Microcontrollers, Analog Temperature Sensors, Power Management - System Supervisors/Voltage Detectors, Voltage References

Notification Subject:

CCB 7643 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP9700B, MCP130, MCP9700, MCP9700A, TC1047A, TC1047, MCP102, MCP9701, MCP9701A, TCM808, MCP1525, MCP1541 device families available in 3L SOT-23 (1.3mm) package at MTAI assembly site.

Affected CPNs:

MFOL-09UGKQ160_Affected_CPN_06122025.pdf
MFOL-09UGKQ160_Affected_CPN_06122025.csv

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP9700B, MCP130, MCP9700, MCP9700A, TC1047A, TC1047, MCP102, MCP9701, MCP9701A, TCM808, MCP1525, MCP1541 device families available in 3L SOT-23 (1.3mm) package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)

Wire Material	Au	CuPdAu
Die Attach Material	8390A	8390A
Molding Compound Material	G600V	G600V
Lead-Frame Material	CDA194	CDA194

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: July 2025

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	June 2025				**July 2025**				
Work Week	23	24	25	26	27	28	29	30	31
Initial PCN Issue Date		X							
Qual Report Availability					X				
Final PCN Issue Date					X				

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: June 12, 2025: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MFOL-09UGKQ160_Qualification_Plan.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

MCP9700BT-H/TT

MCP9700BT-E/TT

MCP130T-270I/TT

MCP130T-300I/TT

MCP130T-315I/TT

MCP130T-450I/TT

MCP130T-460I/TT

MCP130T-475I/TT

MCP130T-485I/TT

MCP130T-450I/TTV02

MCP9700T-H/TT

MCP9700T-E/TT

MCP9700AT-E/TT

TC1047AVNBTR

TC1047VNBTR

MCP102T-195I/TT

MCP102T-195I/TTV01

MCP102T-240E/TT

MCP102T-270E/TT

MCP102T-300E/TT

MCP102T-315E/TT

MCP102T-450E/TT

MCP102T-475E/TT

MCP9701T-E/TT

MCP9701AT-E/TT

TCM808ZENB713

MCP1525T-I/TT

MCP1541T-I/TT